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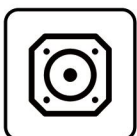
拓電半導體

自主封測 品質把控 售後保障

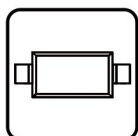
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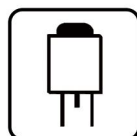
電源管理



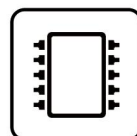
顯示驅動



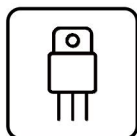
二三極管



LDO穩壓器



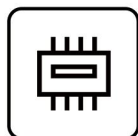
觸摸芯片



MOS管



運算放大器



存儲芯片



MCU



串口通信

SI2302-TD

產品規格說明書

20V N-Channel Enhancement Mode Field Effect Transistor

Description

- Trench Power LV MOSFET technology
- High density cell design for low $R_{DS(ON)}$
- High Speed switching

Application

- Battery protection
- Load switch
- Power management

General Features

- V_{DS} 20V
- I_D 2.3A
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $<75\text{ mohm}$
- $R_{DS(ON)}$ (at $V_{GS}=2.5V$) $<120\text{ mohm}$



SOT-23 Pin Configuration

Package Marking and Ordering Information

Product ID	Package	Marking	QTY(PCS)	Packing method
SI2302-TD	SOT-23	.A2SHB	3000	Reel

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	20	V
Gate-source Voltage	V_{GS}	± 10	V
Drain Current-Continuous	I_D	2.3	A
Pulsed Drain Current ^A	I_{DM}	10	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$	P_D	0.7	W
Thermal Resistance Junction-to-Ambient @ Steady State ^B	$R_{\theta JA}$	178	$^\circ\text{C/W}$
Junction and Storage Temperature Range	T_J, T_{STG}	$-55\sim+150$	$^\circ\text{C}$

20V N-Channel Enhancement Mode Field Effect Transistor

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V,V _{GS} =0V,T _C =25℃			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±10V, V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =250μA	0.45	0.7	0.9	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 4.5V, I _D =2.5A		55	75	mΩ
		V _{GS} = 2.5V, I _D =2.0A		90	120	
Diode Forward Voltage	V _{SD}	I _S =2.5A,V _{GS} =0V			1.2	V
Maximum Body-Diode Continuous Current	I _S				2.8	A
Dynamic Parameters						
Input Capacitance	C _{iss}	V _{DS} =10V,V _{GS} =0V,f=1MHZ		140		pF
Output Capacitance	C _{oss}			39		
Reverse Transfer Capacitance	C _{rss}			22		
Switching Parameters						
Total Gate Charge	Q _g	V _{GS} =4.5V,V _{DS} =10V,I _D =2.5A		2.9		nC
Gate Source Charge	Q _{gs}			0.4		
Gate Drain Charge	Q _{gd}			0.6		
Turn-on Delay Time	t _{D(on)}	V _{GS} =4.5V,V _{DD} =10V, R _L =1.5Ω, R _{GEN} =3Ω		13		ns
Turn-on Rise Time	t _r			54		
Turn-off Delay Time	t _{D(off)}			18		
Turn-off Fall Time	t _f			11		

A. Pulse Test: Pulse Width $\leq 300\mu s$, Duty cycle $\leq 2\%$.

B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

20V N-Channel Enhancement Mode Field Effect Transistor

Typical Characteristics

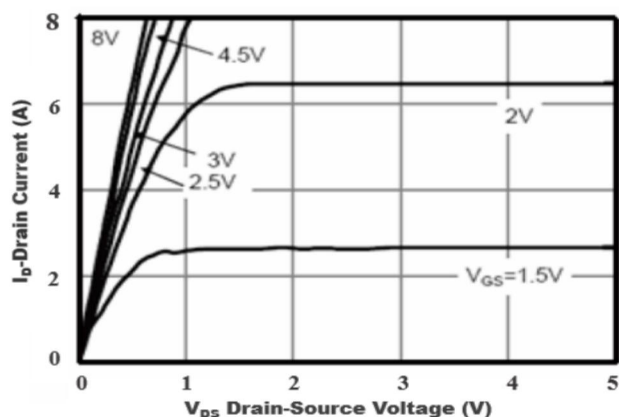


Figure1. Output Characteristics

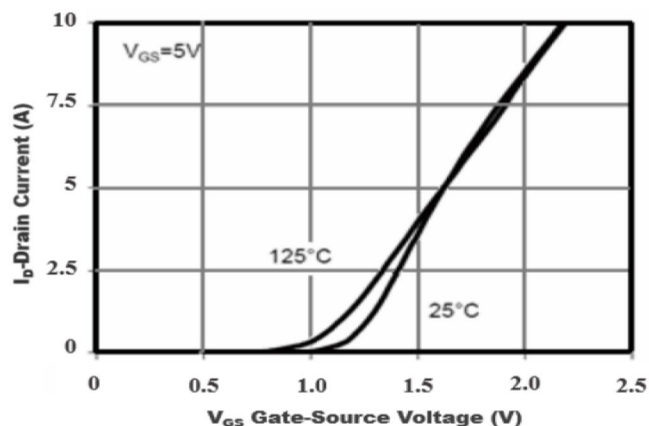


Figure2. Transfer Characteristics

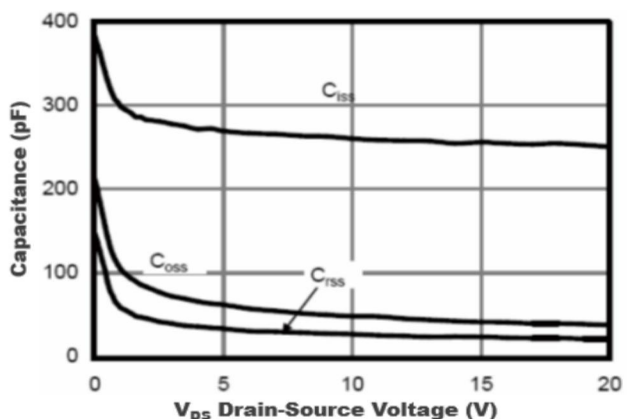


Figure3. Capacitance Characteristics

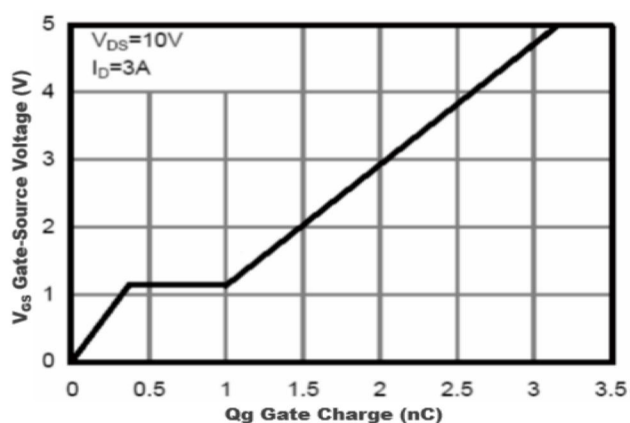


Figure4. Gate Charge

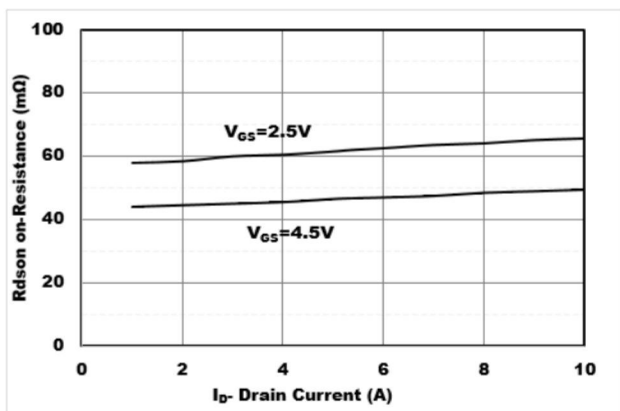


Figure5. Drain-Source on Resistance

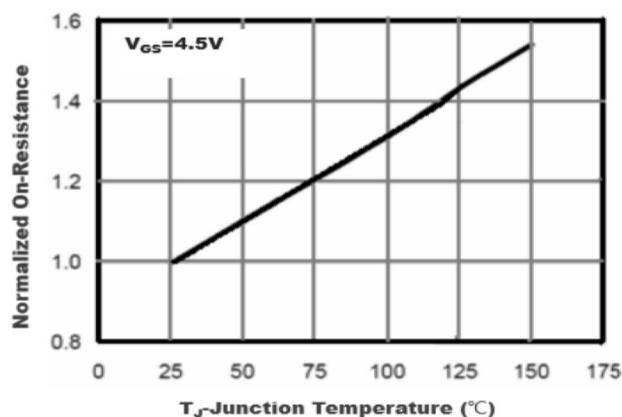


Figure6. Drain-Source on Resistance

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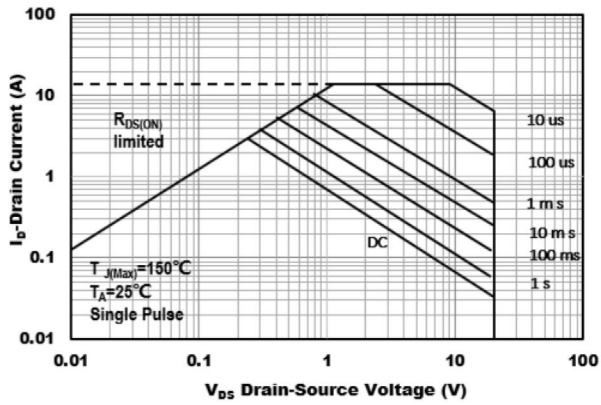


Figure7. Safe Operation Area

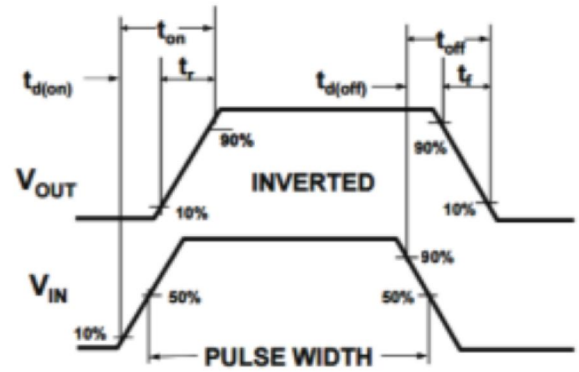
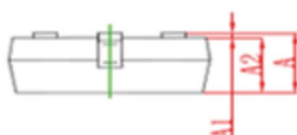
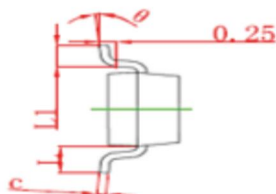
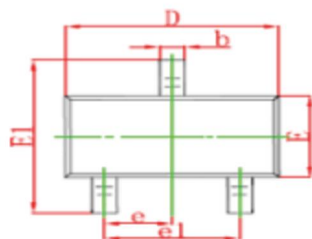


Figure8. Switching wave

20V N-Channel Enhancement Mode Field Effect Transistor

■SOT-23 Package information



Symbol	Dimentions in Millimeter		Dimentions in Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950Type		0.037Type	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.220REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

■SOT-23 Suggested Pad Layout

